1N4148

Small Signal Diode

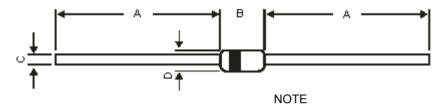




Features:

- High speed silicon switching diodes, axial leaded.
- General purpose, industrial, military and space applications.
- Hermetically sealed glass with a stud on either side of the glass passivated chip provides excellent stability.
- Extremely low leakage and very high reliability.

DO-35 Glass Axial Package



1. Cathode is marked by Band.

Dimensions	Minimum	Maximum
А	25.40	-
В	3.03	4.44
С	0.46	0.56
D	1.52	2.29

Dimensions : Millimetres

Absolute Maximum Ratings (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage	U _{RRM}	100	V	
Reverse Voltage (Continuous)	U _R	75		
Average Forward Current	I _{F(AV)}	150		
Forward Current (DC)	I _F	200		
Repetitive Peak Forward Current	I _{FRM}	450	mA	
Non Repetitive Peak Surge Current tp = 1μ second tp = 1 second	I _{FSM}	2000 500		
Power Dissipation Derating Factor	P _{TA}	500 2.85	mW mW/°C	
Operating and Storage Junction Temperature Range	T _j , T _{stg}	-65 to +200	°C	



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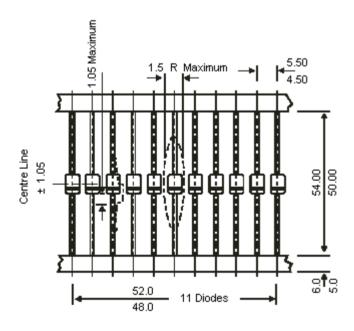
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Electrical Characteristics (T_a = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Minimum	Maximum	Unit
Forward Voltage	U _F	I _F = 10mA	0.65	1.0	V
Reverse Current	I _R	$U_{R} = 20V$ $U_{R} = 75V$ $V_{R} = 20V, T_{j} = 150^{\circ}C$ $V_{R} = 75V, T_{j} = 150^{\circ}C$	-	25 5.0 50 100	nA μA μA μA
Reverse Breakdown Voltage	U _{BR}	I _R = 100μA	100	-	V
Dynamic Characteristics					
Diode Capacitance	C _d	V _R = 0, f = 1MHz	-	4.0	pF
Forward Recovery Voltage	U _{fr}	$I_F = 50 \text{mA}, t_r = 20 \text{ns}$	-	2.5	V
Reverse Recovery Time	t _{rr}	$I_F = 10$ mA, to $I_R = 60$ mA $R_L = 100\Omega$ Measured at $I_R = 1$ mA	-	4.0	ns

DO-35, 52mm Taping Specification



52mm Taping Specification

- 1. T and A indicates axial tape and ammo packing (52mm tape spacing).
- 2. 300mm (minimum) leader tape on every spool.
- 3. Number of empty places allowed 0.25% without consecutive empty places.
- 4. Ends of leads shall preferably not protrude beyond the tapes.
- 5. Components shall be held sufficiently in the tape or tapes so that they can not come free in normal handling.

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